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#### DATASHEET

# CLOCK SLICER USER CONFIGURABLE PECL OUTPUT ZDB

### ICS527-03

#### Description

The ICS527-03 is the most flexible way to generate an output clock from an input clock with zero skew. The user can easily configure the device to produce nearly any output clock that is multiplied or divided from the input clock. The part supports non-integer multiplications and divisions. Using Phase-Locked Loop (PLL) techniques, the device accepts an input clock up to 200 MHz and produces an output clock up to 160 MHz.

The ICS527-03 aligns rising edges on CLKIN with FBPECL at a ratio determined by the reference and feedback dividers.

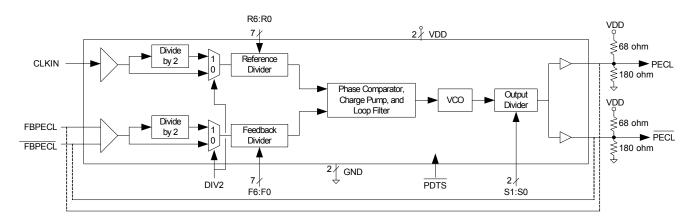
For a PECL input and output clock with zero delay, use the ICS527-04.

#### Features

- Packaged as 28 pin SSOP (150 mil body)
- · Synchronizes fractional clocks rising edges
- CMOS in to PECL out
- Pin selectable dividers
- · Zero input to output skew
- User determines the output frequency no software needed
- Slices frequency or period
- Input clock frequency of 1.5 MHz to 200 MHz
- Output clock frequencies from 2.5 MHz to 160 MHz
- · Very low jitter
- Duty cycle of 45/55
- Operating voltage of 3.3 V
- Advanced, low power CMOS process

NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

#### **Block Diagram**



# **Pin Assignment**

R5		1	28		R4			
R6		2	27		R3			
DIV2		3	26		R2			
S0		4	25		R1			
S1		5	24		R0			
VDD		6	23		VDD			
FBPECL		7	22		PECL			
FBPECL		8	21		PECL			
GND		9	20		GND			
CLKIN		10	19		RES			
PDTS		11	18		F6			
F0		12	17		F5			
F1		13	16		F4			
F2		14	15		F3			
28	28 pin 150 mil body SSOP							

### **Pin Descriptions**

# Output Frequency and Output Divider Table

S1	<b>S</b> 0	Output Divider	Output Frequency (MHz)
0	0	2	10 - 80
0	1	4	5 - 40
1	0	8	2.5 - 20
1	1	1	20 -160

Pin Number	Pin Name	Pin Type	Pin Description
1,2, 24-28	R5, R6, R0-R4	Input	Reference divider word input pins determined by user. Forms a binary number from 0 to 127. Internal pull-up.
3	DIV2	Input	Selects CLK2 function to output a SYNC signal or a divide by 2 of CLK1 based on the table above. Internal pull-up.
4, 5	S0, S1	Input	Select pins for output divider determined by user. See table above. Internal pull-up.
6, 23	VDD	Power	Connect to +3.3 V.
7	FPECL	Input	PECL feedback input.
8	FPECL	Input	Complementary PECL feedback input.
9, 20	GND	Power	Connect to ground
10	CLKIN	Input	Clock input.
11	PDTS	Input	Power Down. Active low. Turns off entire chip when low, both clock outputs are tri-stated. Internal pull-up.
12-18	F0-F6	Input	Feedback divider word input pins determined by user. Forms a binary number from 0 to 127. Internal pull-up
19	RES	BIAS	Resistor connection to VDD for setting level of PECL outputs.
21	PECL	Output	Complementary PECL input clock.
22	PECL	Output	PECL input clock.

#### **External Components**

#### **Decoupling Capacitors**

As with any high performance mixed-signal IC, the ICS527-03 must be isolated from system power supply noise to perform optimally.

Decoupling capacitors of  $0.01\mu$ F must be connected between each VDD and the PCB ground plane. They must be connected close to the device to minimize lead inductance.

#### **Series Termination Resistor**

Clock output traces over one inch should use series termination. To series terminate a  $50\Omega$  trace (a commonly used trace impedance), place a  $33\Omega$  resistor in series with the clock line, as close to the clock output pin as possible. The nominal impedance of the clock output is  $20\Omega$ 

# Determining (setting) the ICS527-03 Dividers

The user has full control in setting the desired output clock over the range shown in the table on page 2. The user should connect the divider select input pins directly to ground (or VDD, although this is not required because of internal pull-ups) during Printed Circuit Board layout, so the ICS527-03 automatically produces the correct clock when all components are soldered. It is also possible to connect the inputs to parallel I/O ports in order to switch frequencies.

The output of the ICS527-03 can be determined by the following simple equation:

FB Frequency = Input Frequency  $\times \frac{FDW + 2}{RDW + 2}$ 

Where:

(

Reference Divider Word (RDW) = 0 to 127 Feedback Divider Word (FDW) = 0 to 127 FB Frequency is the same as either CLK1 or CLK2 depending on feedback connection

Also, the following operating ranges should be observed:

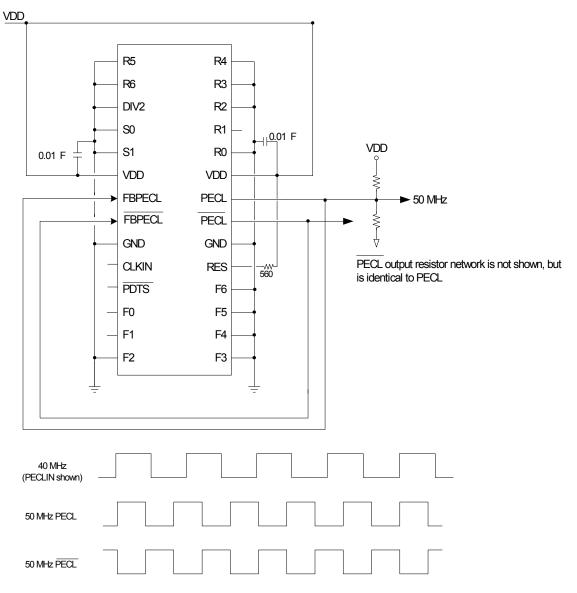
The output divide should be selected depending on the frequency of CLK1. The table on page 2 gives the ranges.

The dividers are expressed as integers. For example, if a 50 MHz output on CLK1 is desired from a 40 MHz input, the reference divider word (RDW) should be 2 and the feedback divider word (FDW) should be 3 which gives the required 5/4 multiplication. If multiple choices of dividers are available, then the lowest numbers should be used. In this example, the output divide (OD) should be selected to be 2. Then R6:R0 is 0000010, F6:F0 is 0000011 and S1:S0 is 00. Also, this example assumes CLK1 is connected to FBIN.

If you need assistance determining the optimum divider settings, please send an e-mail to ics-mk@icst.com with the desired input clock and the desired output frequency.

#### **Typical Example**

The following connection diagram shows the implementation of the example from the previous section. This will generate a 50 MHz clock synchronously with a 40 MHz input. The layout diagram below will produce the waveforms shown on the right.



Note: The series termination resistor is located before the feedback

### **PCB Layout Recommendations**

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

1) Each 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No via's should be used between decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via.

2) PECL termination networks should be located as close to the outputs as possible.

3) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers. Other signal traces should be routed away from the ICS527-03. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

# **Absolute Maximum Ratings**

Stresses above the ratings listed below can cause permanent damage to the ICS527-03. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	7V
All Inputs and Outputs	-0.5V to VDD+0.5V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Junction Temperature	175°C
Soldering Temperature	260° C

#### **Recommended Operation Conditions**

Parameter	Min.	Тур.	Max.	Units
Ambient Operating Temperature, ICS527R-02	0		+70	°C
Ambient Operating Temperature, ICS527R-02I	0		+70	°C
Power Supply Voltage (measured in respect to GND)	+3.15	+3.3	+3.45	V

### **DC Electrical Characteristics**

Unless stated otherwise, VDD = 3.3V  $\pm$ 5%, Ambient Temperature 0 to +70°C

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Operating Voltage	VDD		3.15	3.3	3.45	V
Supply Current	IDD	15 MHz in, 60MHz out, no load		15		mA
Supply Current, Power Down	IDDPD	PDTS=0		20		μA
Input High Voltage	V <sub>IH</sub>		2			V
Input Low Voltage	V <sub>IL</sub>				0.8	V
Input High Voltage, PECLIN and FBIN	V <sub>IH</sub>		VDD/2+1			V
Input Low Voltage, PECLIN and FBIN	V <sub>IL</sub>				VDD/2-1	V
Output High Voltage	V <sub>OH</sub>	I <sub>OH</sub> = -12 mA	2.4			V
Output Low Voltage	V <sub>OL</sub>	I <sub>OL</sub> = 12 mA			0.4	V

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Capacitance, except PECLIN and FBIN	C <sub>IN</sub>			5		pF
Short Circuit Current	I <sub>OS</sub>			±70		mA
On-chip pull-up resistor	R <sub>PU</sub>			270		kΩ

#### **AC Electrical Characteristics**

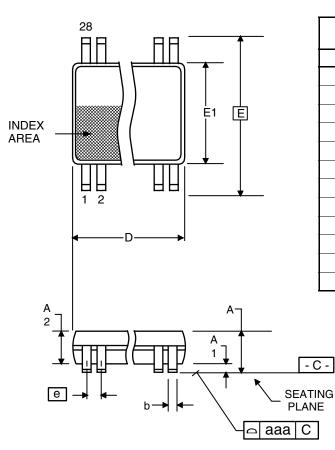
Unless stated otherwise, VDD =  $3.3V \pm 5\%$ , Ambient Temperature 0 to  $+70^{\circ}C$ 

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Units
Input Frequency	F <sub>IN</sub>		1.5		200	MHz
Output Frequency, CLK1	F <sub>OUT</sub>	0 to +70° C	2.5		160	MHz
		-40 to +85° C	4		140	MHz
Output Rise Time	t <sub>OR</sub>	0.8 to 2.0V, C <sub>L</sub> =15pF		1		ns
Output Fall Time	t <sub>OF</sub>	2.0 to 0.8V, C <sub>L</sub> =15pF		1		ns
Output Duty Cycle (% high time)	t <sub>OD</sub>	Measured at VDD/2, C <sub>L</sub> =15pF	45	50	55	%
Power Down Time, PDTS low to clocks tri-stated					50	ns
Power Up ime, PDTS high to clocks stable					10	ms
Absolute Clock Period Jitter	t <sub>ja</sub>	Deviation from mean		± 90		ps
One sigma Clock Period Jitter	t <sub>js</sub>			40		ps
Input to output skew	t <sub>IO</sub>	PECLIN to CLK1, Note 1	-250		250	ps
Device to device skew	t <sub>pi</sub>	Common PECLIN, measured at FBIN		0	500	ps

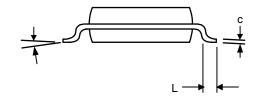
Note 1: Assumes clocks with same rise time, measured from rising edges at VDD/2.

#### Package Outline and Package Dimensions (28 pin SSOP, 150 mil Body, 0.025 mm Pitch)

Package dimensions are kept current with JEDEC Publication No. 95, MO-153



	Millimeters		Inc	hes
Symbol	Min	Max	Min	Max
A	1.35	1.75	.053	.069
A1	0.10	0.25	.0040	.010
A2		1.50		.059
b	0.20	0.30	.008	.012
С	0.18	0.25	.007	.010
D	9.80	10.00	.386	.394
E	5.80	6.20	.228	.244
E1	3.80	4.00	.150	.157
е	0.635 Basic		0.025 Basic	
L	0.40	1.27	.016	.050
α	<b>0</b> °	<b>8</b> °	<b>0</b> °	<b>8</b> °
aaa		0.10		0.004



#### **Ordering Information**

Part / Order Number	Marking	Shipping packaging	Package	Temperature
527R-03*	ICS527R-03	Tubes	28 pin SSOP	0 to +70° C
527R-03T*	ICS527R-03	Tape and Reel	28 pin SSOP	0 to +70° C
527R-03LF	527R-03LF	Tubes	28 pin SSOP	0 to +70° C
527R-03LFT	527R-03LF	Tape and Reel	28 pin SSOP	0 to +70° C

# \*NOTE: EOL for non-green parts to occur on 5/13/10 per PDN U-09-01

#### "LF" denotes Pb free packaging, RoHS compliant

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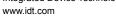
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